

08-22-2000

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FORM PTO-1595

RECC



EXPRESS MAIL NO.: T U.S. DEPARTMENT OF COMMERCE

101438440

1. Name of Party(ies) conveying party(ies)

1. MU-CHUN WANG; 2. SHIH-CHIEH KAO;
3. SHIANG HUANG-LU; AND 4. YUAN-CHANG LIU

Additional Name(s) of conveying party(ies) attached? [] Yes [X] No

2. Names and address of party(ies) receiving an interest:

Name: UNITED MICROELECTRONICS CORP.

Internal Address:

Street Address: NO. 3, LI - HSIN RD. II, SCIENCE BASED INDUSTRIAL PARK

City: HSINCHU State: Zip: TAIWAN, R.O.C.

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other _____

Additional name(s) & address(es) attached? [] Yes [X] No

Execution Date: JULY 14, 2000

4. Application number(s) or patent number(s): N / A

If this document is being filed together with a new application, the execution date of the application is:

JULY 14, 2000

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? [] Yes [X] No

5. Name and Address of party to whom correspondence concerning document should be mailed:

Name: CHARLES C.H. WU

Internal Address:

Street Address: 7700 IRVINE CENTER DRIVE SUITE 710

City: IRVINE State: CA Zip: 92618-3043

6. Total Number of applications and registrations involved: [1]

7. Total fee (37 CFR 2.6(b)(6)) [\$40.00]
 Enclosed
 Authorized to be charged to deposit account

8. Deposit account number:

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the forgoing information is true and correct and any attached copy is a true copy of the original document.

CHARLES C.H. WU

Name of Person Signing

Signature

JULY 26, 2000

Date

Total number of pages including cover sheet, attachments, and document: [4]

08/21/2000 MTHA11

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Mail documents to be recorded with required cover sheet information to:
40.00 DC Commissioner of Patents and Trademarks, Box Assignments

01 FC:581

jc869 U.S. PTO 09/626409



ASSIGNMENT

WHEREAS,

- | | |
|--------------------|-------------------|
| 1. Mu-Chun Wang | 2. Shih-Chieh Kao |
| 3. Shiang Huang-Lu | 4. Yuan-Chang Liu |

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **VIA-PLUG LAYOUT STRUCTURE FOR CONNECTING DIFFERENT METALLIC LAYERS**

Filed: Serial No.

Executed concurrently with the execution of this instrument

WHEREAS, United Microelectronics Corp.
of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

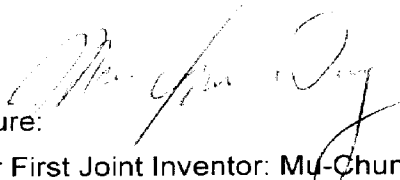
hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

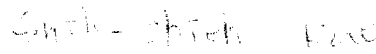
Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

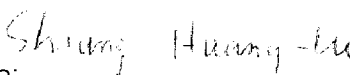
IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.


Signature:
Sole or First Joint Inventor: Mu-Chun Wang


Date: July 14, 2000


Signature:
Second Joint Inventor (if any): Shih-Chieh Kao

Date: July 14, 2000


Signature:
Third Joint Inventor (if any): Shiang Huang-Lu

Date: July 14, 2000


Signature:
Fourth Joint Inventor (if any): Yuan-Chang Liu

Date: July 14, 2000